

ABS1-10~ABS10-10

Rev.B Jun.-2023

描述 / Descriptions

1A 表面贴装玻璃钝化整流桥，薄型 ABS/LBF 封装。

1A Surface Mount Glass Passivated Bridge Rectifier, ABS/LBF thin package.

特征 / Features

玻璃钝化芯片，浪涌电流大，反向电压：100V~1000V 正向电流：1A，适用于表面贴装，无卤产品。

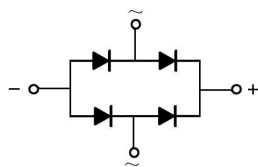
Glass Passivated Chip Junction, Reverse Voltage :100 to 1000V, Forward Current: 1A, High Surge Current Capability, Designed for Surface Mount Application, HF Product.

用途 / Applications

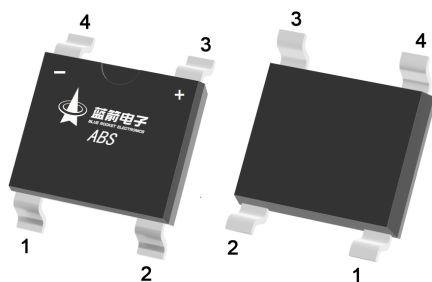
一般用途。

General purpose.

内部等效电路 / Equivalent Circuit

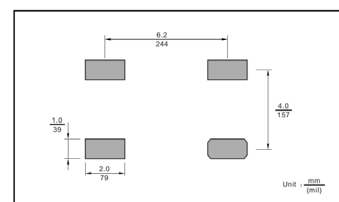


引脚排列 / Pinning



PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)

The recommended mounting pad size



印章代码 / Marking

见印章说明。 See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating						单位 Unit
		ABS1-10	ABS2-10	ABS4-10	ABS6-10	ABS8-10	ABS10-10	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at $T_c=125^\circ\text{C}$	I_o	1						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	35						A
Typical Junction Capacitance ^(Note1)	C_i	13						pF
Typical Thermal Resistance ^(Note2)	$R_{\theta JA}$	72						$^\circ\text{C}/\text{W}$
	$R_{\theta JC}$	20						$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	T_j, T_{stg}	-55~150						$^\circ\text{C}$

Note:

1. Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. Mounted on glass epoxy PC board with $4 \times 1.5'' \times 1.5''$ (3.81×3.81 cm) copper pad.

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating	单位 Unit
Forward Voltage per element	V_F	$I_F=1\text{A}$	1.1	V
Maximum DC Reverse Current at Rated DC Blocking Voltage	I_R	$T_a=25^\circ\text{C}$	5	μA
		$T_a=100^\circ\text{C}$	50	
		$T_a=125^\circ\text{C}$	100	

电参数曲线图 / Electrical Characteristic Curve

Fig.1 Average Rectified Output Current Derating Curve

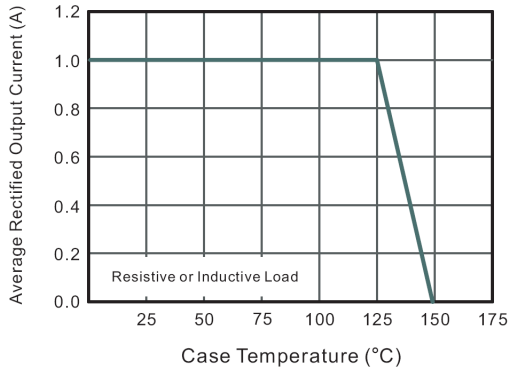


Fig.2 Typical Reverse Characteristics

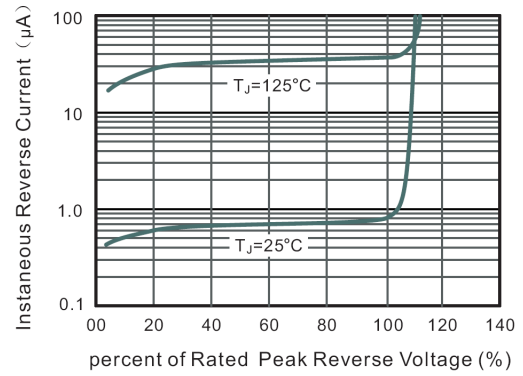


Fig.3 Typical Instaneous Forward Characteristics

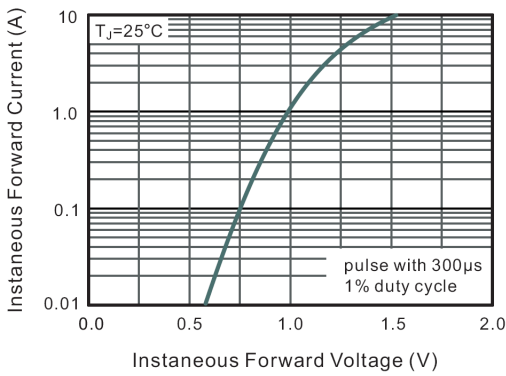


Fig.4 Typical Junction Capacitance

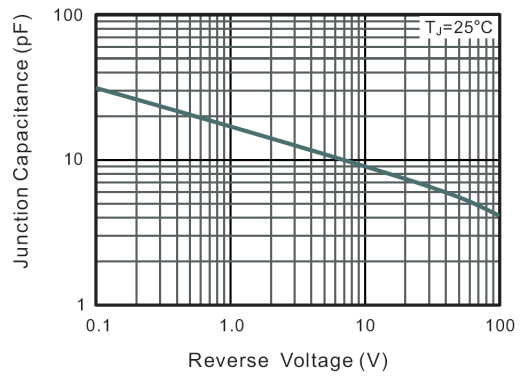
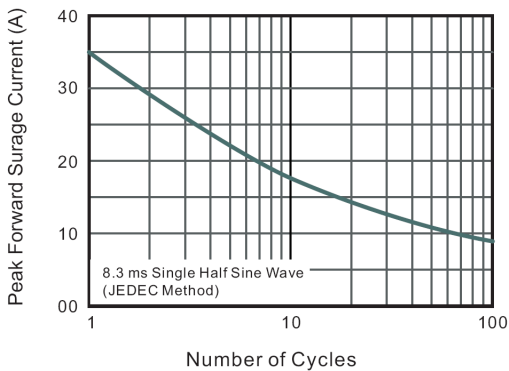
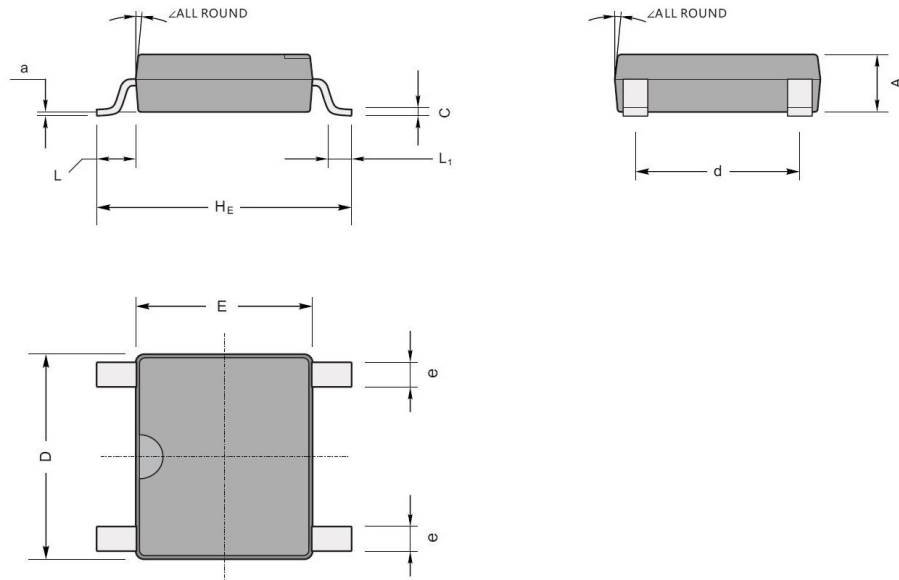


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



外形尺寸图 / Package Dimensions

ABS/LBF



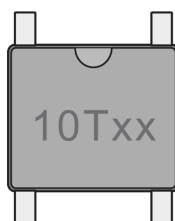
ABS/LBF mechanical data

UNIT		A	C	D	E	H_E	d	e	L	L_1	a	\angle
mm	max	1.5	0.22	5.2	4.5	6.4	4.2	0.7	0.95	0.6	0.2	7°
	min	1.3	0.15	4.9	4.2	6.0	3.8	0.5				
mil	max	59	8.7	205	177	252	165	28	37	24	8	
	min	51	5.9	193	166	236	150	20				

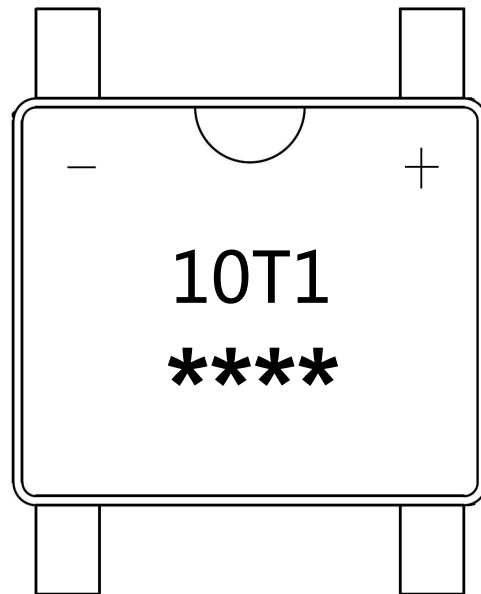
印章说明 / Marking Instructions

Marking

Type number	Marking code
ABS1-10	10T1
ABS2-10	10T2
ABS4-10	10T4
ABS6-10	10T6
ABS8-10	10T8
ABS10-10	10T10



印章说明 / Marking Instructions



说明：

10T1： 为型号代码

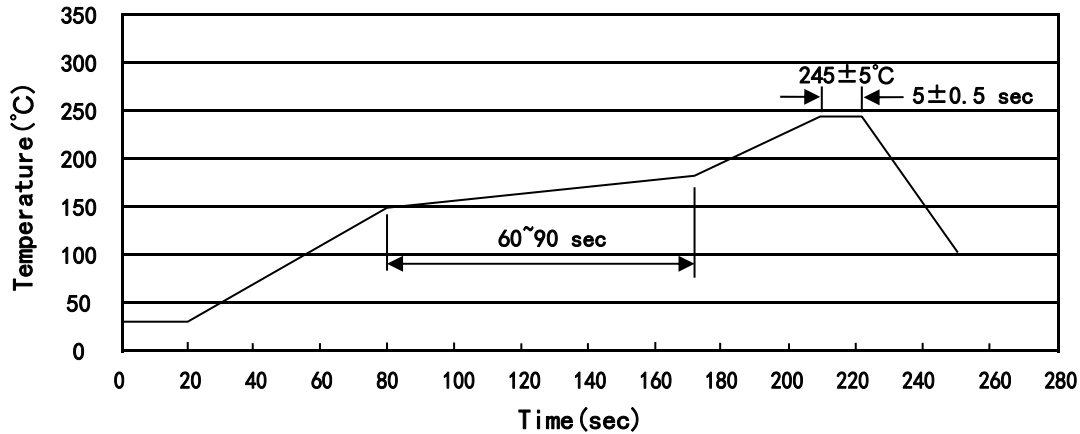
****： 为生产批号追溯码，第1个*为年月代码，后面3个*为当月小批号代码

Note:

10T1： Product Type Code

****： Lot No. Code , The 1st * means:YM Code , The last 3 * means:little Lot No Code

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 150~180°C，时间 60~90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2~10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
ABS/LBF	5,000	2	10,000	7	70,000	13" ×12	336X336X40	380X335X366

使用说明 / Notices